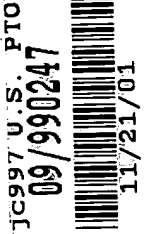


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E. Willis  
5-24-02



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In the U.S. Patent Application of:	) Examiner:
Inventor(s) : Binneg Y. Lao et al.	)
Serial No. :	) Art Unit:
Filing Date :	)
For : Single and Multiple Layer	)
Packaging of High-	)
Speed/High-Density ICs	)

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INFORMATION DISCLOSURE STATEMENT  
UNDER 37 CFR 1.97(b)

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

This Information Disclosure Statement is submitted with Disclosure Form PTO-1449 with attached copies of the references. The references disclosed are submitted in compliance with the duty of disclosure as defined in 37 CFR § 1.56. The Examiner is requested to consider and make the references of official record in the Application.

The submission of the above-indicated references is not to be construed as a representation that an exhaustive search has been made, that additional information material to the examination of this Application does not exist, or that the references, either alone or in combination with other references, constitute prior art under 35 U.S.C. § 102 or § 103.